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Bib Data Sheet

SERIAL NUMBER 10/500,119	FILING OR 371(c) DATE 06/17/2005 RULE	CLASS 174	GROUP ART UNIT 2841	ATTORNEY DOCKET NO. 1204.43988X00	
APPLICANTS Hidehiro Nakamura, Tsukuba-shi, JAPAN; Akishi Nakaso, Oyama-shi, JAPAN; Shigeharu Arike, Shimodate-shi, JAPAN; Fumio Inoue, Tsukuba-shi, JAPAN; Tetsuya Enomoto, Tsukuba-shi, JAPAN; Norio Moriike, Shimodate-shi, JAPAN; Kousuke Hiroki, Tsukuba-shi, JAPAN;					
** CONTINUING DATA ***** This application is a 371 of PCT/JP02/13434 12/24/2002					
** FOREIGN APPLICATIONS ***** JAPAN 2001-391799 12/25/2001 JAPAN 2002-126594 04/26/2002 JAPAN 2002-230095 08/07/2002					
Foreign Priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 (a-d) conditions <input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after met Allowance Verified and Acknowledged <u>Examiner's Signature</u> <u>Initials</u>		STATE OR COUNTRY JAPAN	SHEETS DRAWING 8	TOTAL CLAIMS 39	INDEPENDENT CLAIMS 2
ADDRESS 020457					
TITLE Connection substrate, multi-layer wiring board using the connection substrate, substrate for semiconductor package, and methods for manufacturing them					
FILING FEE RECEIVED 2492	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit		